| Part Number | USB3140 | | Rev | | A1 | Date | 31/07/17 |
|------------------------|---|---|-----|---------|----|----------|----------|
| Product Description | Micro USB Receptacle, Ty Hole Shell Stakes | Micro USB Receptacle, Type B, 5 Pins, SMT, Vertical, with Through- Hole Shell Stakes | | | | | |
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1.0 SCOPE.

This specification covers performance, tests and quality requirements for the Micro USB Receptacle USB3140(Type B, SMT, Vertical).

2.0 PRODUCT NAME AND PART NUMBER.

Micro USB Receptacle, 5 Pins, SMT, Type B: USB3140.

3.0 PRODUCTSHAPE, DIMENSIONS AND MATERIAL.

Please refer to drawings.

4.0 RATINGS.

4.1 Current rating: Signal (Pins 2, 3, 4) 1.0A

Power (Pins1, 5)..... 1.8A

4.2 Voltagerating 30V AC

4.3 Operating Temperature Range-30°C to +85°C

5.0 TEST AND MEASUREMENT CONDITIONS.

Product is designed to meet electrical, mechanical and environmental performancerequirements specified in Paragraph 6.0. All tests are performed in ambient conditions unless otherwise specified.

6.0 PERFORMANCE.

| ltem | | Requirement | |
|-------------------|--|---|---|
| Examination of Pr | | sual, dimensional and inspection as per quality plan. | Product shall meet requirements of product drawing and specification. |



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6.1 Electrical Performance.

| Item | Test Condition | Requirement |
|--|--|---------------|
| Low-signal Level Contact Resistance | When measured at 20mV maximum open circuit at 100mA. Mated test contacts must be in a connector housing In accordance withEIA-364-23. | 30 mΩ Max. |
| Insulation Resistance | Mate/Un-mate connectors, apply 100V DC for 1 minute at sea level between adjacent terminal or ground. In accordance with EIA-364-21. | 1000 MΩ Min. |
| Dielectric Strength | Mate/Un-mate connectors, apply 100V ACfor 1 minute at sea level. In accordance with EIA-364-20. | No Breakdown. |

6.2Mechanical Performance.

| Item | Test Condition | Requirement |
|------------------------|--|---|
| Mating/Un-mating Force | Mate/Un-mated at a rate of 12.5mm/min. In accordance with EIA-364-13. | Mating force: 35N Max. Un-Mating force: 8N Min. to 25NMax. |
| Durability | 10,000 cycles at a cycle rate of 500 cycles per hour if done automatically and 200 if manual cycles. In accordance with EIA-364-09. | Mating force: 35N Max. Un-Mating force: 8N Min. to 25N Max Low Level Contact Resistance: 30mΩ Max. |
| Vibration | Mate connectors and subject to 5.35 Gs RMS. For a period of 15 minutes in each of the 3 mutually perpendicular axes. In accordance with EIA-364-28 Test condition V test letter A. | Appearance: No Damage. Contact Resistance: 50 m Ω Max. Discontinuity: 1.0 μ second Max. |
| Mechanical Shock | Mate connectors and subject to the following shock conditions, 3 shocks shall be applied along 3 mutually perpendicular axis (Total of 18 shocks). Test Pulse at Half Sine Peak Value: 294 m/s ² (30G) Duration: 11ms. In accordance with EIA-364-27. Test condition H. | Appearance: No Damage. Contact Resistance: 10 mΩ Max. Change allowed. Discontinuity: 1.0 μ second Max. |



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| Item | Test Condition | Requirement |
|--|---|--|
| Humidity Test | Subject mated connectors to Duration: 168 hours temperature between -25°C to +65°C with 90 to 95% RH. In accordance with EIA-364-31. Test condition A method III | Appearance: No Damage. Contact Resistance: 10 mΩ Max. change allowed. Insulation Resistance: 1000 MΩ Min. Dielectric Strength: No Breakdown |
| Salt Spray | Subject mated/unmated connectors to 5% salt-solution concentration, 35°C for 48 hours. In accordance with EIA-364-26, Test Condition B. | Low Level Contact Resistance: 50mΩ Max. No visible rust |
| Temperature Life | Subject mated connectors to temperature life at +85°C for 96hours. In accordance with EIA-364-17. Test condition 2 Method A. | Contact Resistance: 10 mΩ Max.Change allowed. Insulation Resist: 1000 MΩ Min.Shall meet visual requirement and show no physical damage. |
| Temperature Rise | Mate connector and measure the temperature rise of contact when the maximum rated current is passed and in accordance with EIA-364-70. | +30°C Max. Change allowed. |
| Thermal Shock | Mate module and subject to follow condition for 10 cycles. At -55°C to +85°C. In accordance with EIA-364-32, test condition I. | No Damage 10mΩ Max. change allowed. Insulation Resist: 1000 MΩ Min. Dielectric Strength: No Breakdown |
| Solderability | Dip solder-tails in flux then immerse in solder bath at 245 ±5°C up to 0.5mm from the bottom of the housing for 4~5 seconds. In accordance with EIA-364-52, category 2. | 95% of immersed area must show no voids, pin holes. |
| Resistance to Soldering Heat (Reflow Soldering) | Sample mounted on PCB and subject to solder bath method, Temperature:260°C for 10±1 sec In accordance with EIA-364-56. | Without deformation of shell or excessive looseness of the terminals (pin.) |
| Resistance to Soldering Heat (Hand Soldering) | Sample mounted on PCB and subject to hand iron soldering, Temperature:350±10°C for 3±1 sec | Without deformation of shell or excessive looseness of the terminals (pin.) |
| Resistance to Solder Heat (Wave Soldering) | Heat: 260±5°C, 10+2/-0 sec. In accordance with EIA-364-56 | Without deformation of shell or excessive looseness of the terminals (pin.) |



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8.0 PRODUCT QUALIFICATION AND TEST SEQUENCE

| Test Item | Test Group | | | | | | | | | |
|-------------------------------------|------------|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Test tiell | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 |
| Examination of Product | | | | 1,6 | 1,6 | 1,4 | 1,3 | 1,3 | 1,3 | 1,3 |
| Low-signal Level Contact Resistance | | 1,5 | 1,4 | 2,9 | 2,9 | 2,5 | | | | |
| Insulation Resistance | | | | 3,8 | 3,8 | | | | | |
| Dielectric Withstanding Voltage | | | | 4,7 | 4,7 | | | | | |
| Mating / Unmating Forces | | 2,4 | | | | | | | | |
| Durability | | 3 | | | | | | | | |
| Vibration | | | 2 | | | | | | | |
| Mechanical Shock | | | 3 | | | | | | | |
| Humidity | | | | 5 | | | | | | |
| Salt Spray | | | | | | 3 | | | | |
| Temp Life | | | | | 5 | | | | | |
| Temp Rise | 1 | | | | | | | | | |
| Thermal Shock | | 4 | | | | | | | | |
| Solderability | | | | | | | 2 | | | |
| Resistance to Wave Soldering Heat | | | | | | | | 2 | | |
| Resistance to HandSoldering Heat | | | | | | | | | 2 | |
| Resistance to ReflowSoldering Heat | | | | | | | | | | 2 |

